Introduction to the Phase 2 electronics

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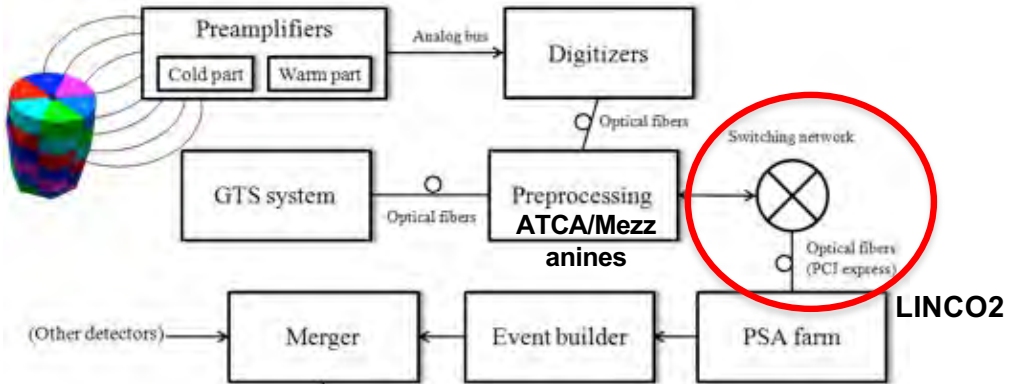
Outline

- AGATA Electronics Evolution
- Known Issues
- Guidelines
- General Description
- Power Supply Unit
- Mechanical Layout
- Work Status
- Conclusions

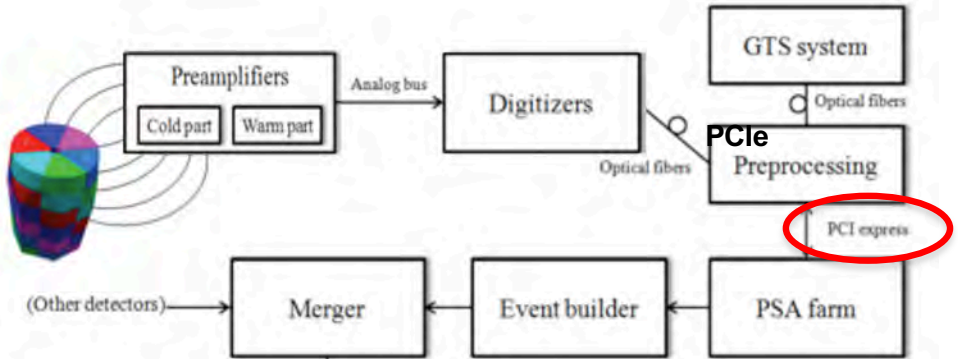
AGATA Electronics Evolution

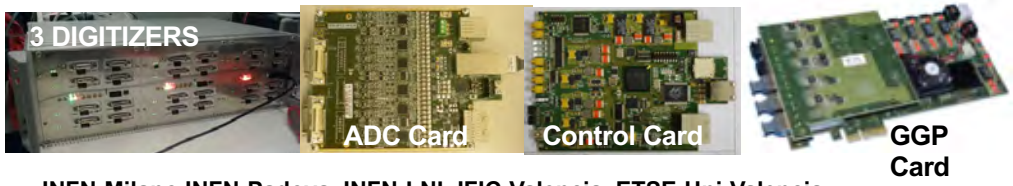
AGATA Electronics Phase 0/Early1 (23 - 25 ch available)



IPHC Strasbourg Uni.Liverpool STFC Daresbury IPNO, CSNSM-Orsay INFN-Padova

AGATA Electronics Advanced Phase 1 (13 ch available)





INFN-Milano INFN-Padova INFN-LNL IFIC-Valencia ETSE-Uni-Valencia

New production batch of Adv. Phase 1 electronics
10 channels + spares

We need to go for 4π AGATA (3π for the moment)

Known Issues

Issues suffered in AGATA Electronics evolution

At least:

- Component obsolescence (transceivers, IC, …)
- Compatibility issues, i.e. GGP and workstations
- Difficulties in HR for maintenance and repairing
- Costs increasing for old components
- …

We had guidelines from experts for the AdvPh1 (2012) which could be extended to the new Phase 2. Basically,

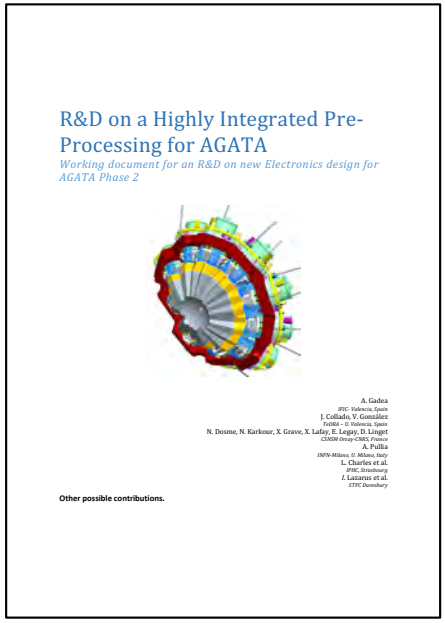
- **Increase integration**
- **Reduce production and maintenance costs**
- **Keep backward compatibility of each generation FEE and with GTS.**

Guidelines

Objective: to build a scalable and stable Back End Electronics and DAQ (Electronic Data Acquisition) system for AGATA beyond phase 1

Important issues

- Interface between front end electronics and servers should **not rely on any specific hardware interface**.
- Simplified and autonomous electronic modules to **ease maintenance** and **minimize impact of possible rework due to obsolete components** in future.
- **Highly integrated solution** to ease the installation in experimental area.
- **Readout** based on **high bandwidth network technology** (up to 10 Gb/s per crystal).
- **Stable and scalable architecture** of the AGATA BEE&DAQ architecture (for which the necessary performances must be fulfilled from 45 up to 180 crystals)


R&D on a Highly Integrated Pre-Processing for AGATA

Working document for an R&D on new Electronics design for AGATA Phase 2

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Other possible contributions.

Guidelines

Important issues (cont'd)

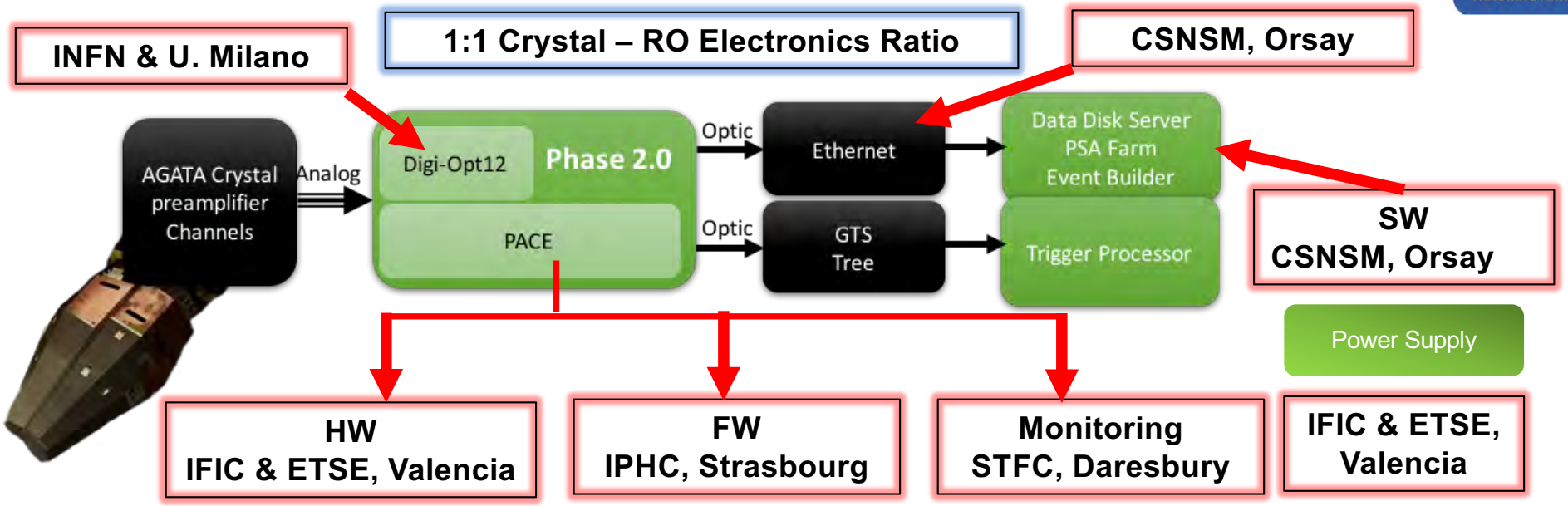
- **Modularity** to allow for the use of new technologies when available and suitable for the objectives of cost reduction and higher integration.
- **Maintenance** of the system **by external companies highly recommended** to insure it through the life of the experiment independently of man power fluctuations in the collaboration.
- **Possibility to have a portable version** to install them in Scanning area, Acceptance Test labs, Host labs for detector maintenance labs so that results can be compared using the same instrumentation between experimental area and labs.
- **Built-in self tests and built in embedded software** so that the system can work **without network access to servers and complicated infrastructure**.

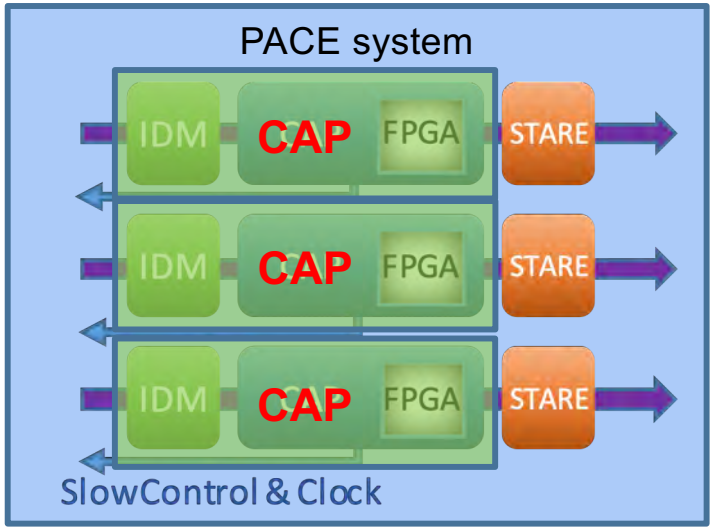
Version evolution

- **2.0:** new architecture with same functionalities as AdvPh1.
- **2.1:** new functionalities to the system
- **2.2:** R&D on the improvement of ADC quality, new trigger/sync systems, Digital Pre-amplifier, …

General Description

Final General Layout

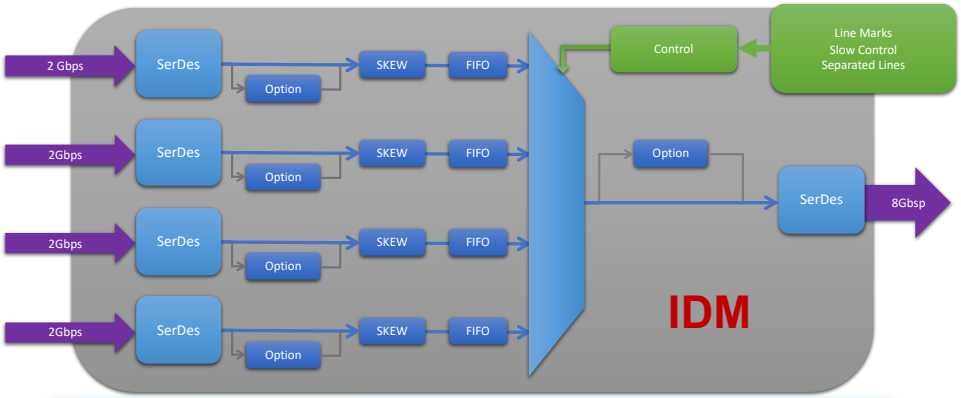


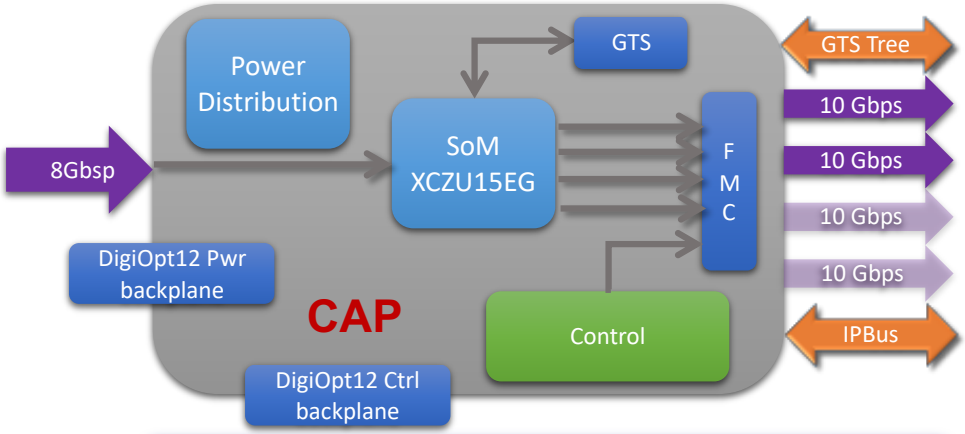


- **PACE:** Processing and Control over Ethernet
  - **CAP-IDM:** Data aggregation and Control and Processing: integrates the **Control Card and GGP** functionalities **plus GTS** leaf interface
  - **STARE:** Serial Transfer Acquisition Readout over Ethernet: 10 Gb/s Ethernet mezzanine.

General Description

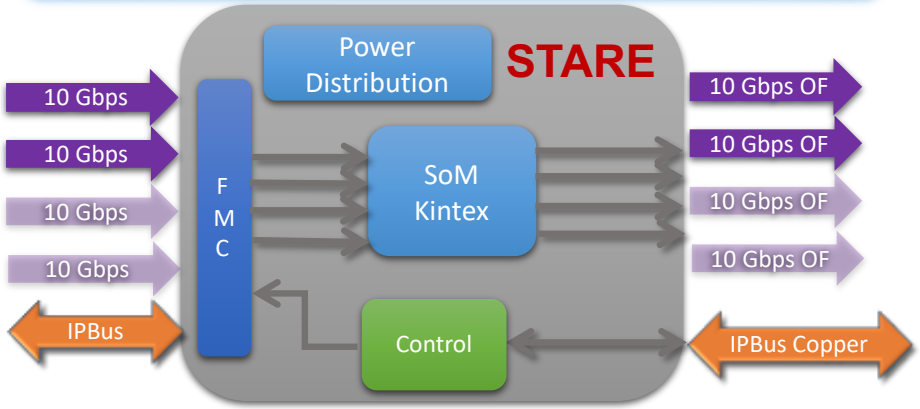
PACE Block Diagram Functional Layout





Main features

- Cooper connection to DigiOPT12
- Reduce the number of GTH transceivers
- 4:1 channel aggregation TLK10022



Main features

- SOM module Zynq Ultrascale FPGA. Compared to GGP Virtex
  - ~ 3 times more logic cells
  - ~ 1.5 times more BRAM
  - ~ 3.8 times more DRAM
  - ~ 6 times more DSP
- 10 year support from manufacturer (Trenz Electronics)

Main features

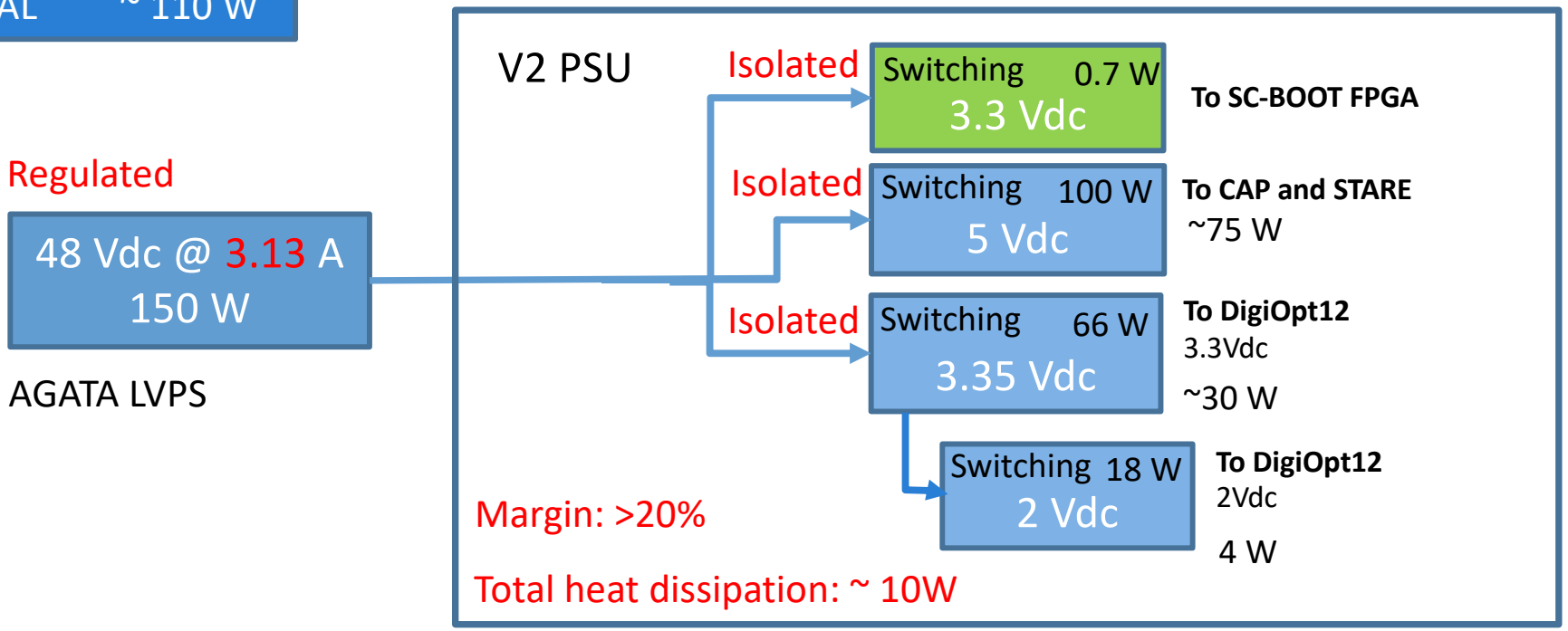
- Multiple 10 Gbps Ethernet data output
  - Data readout
  - Monitoring, inspection, …

Power Supply Unit

V2 DIGITIZER BOX POWER ESTIMATION

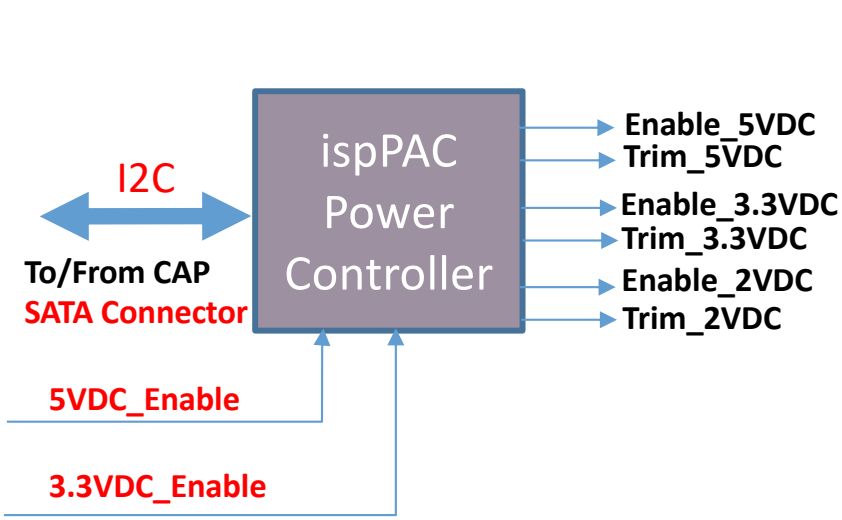
4 x DIGIOpt12 (no optical trx)	~34 W
1 x CAP + STARE	75 W
1 x CAP SC-BOOT FPGAS	0.7 W
1 x STARE	20 W
TOTAL	~ 110 W

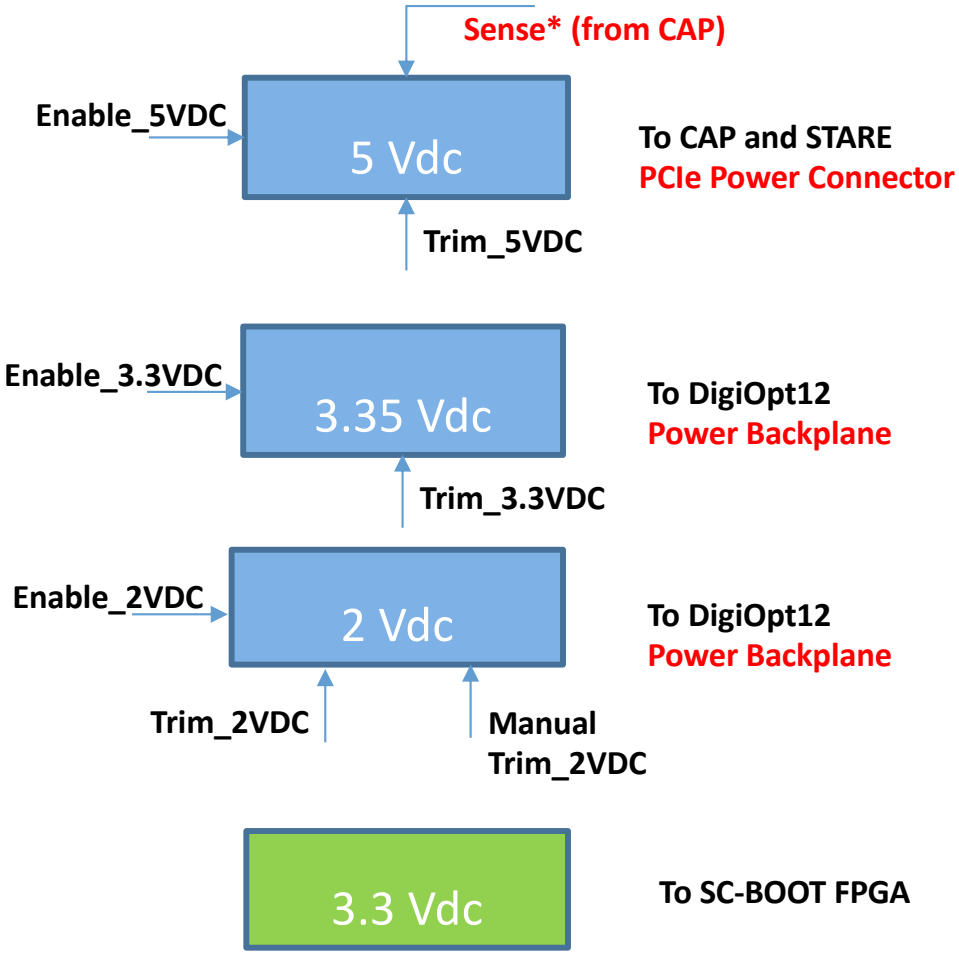
Design requirements:
- Cooling ~18 W diss.
- Ground isolation from LVPS input
- Slow control



Power Supply Unit

V2 PSU Slow Control



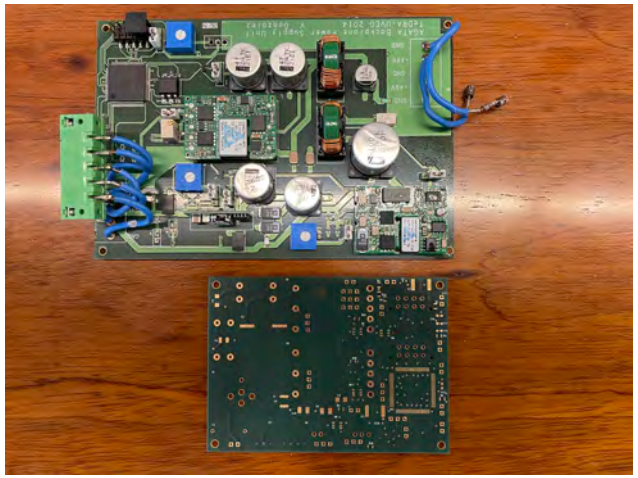


V2 PSU Dimensions

133 x 90 mm^2

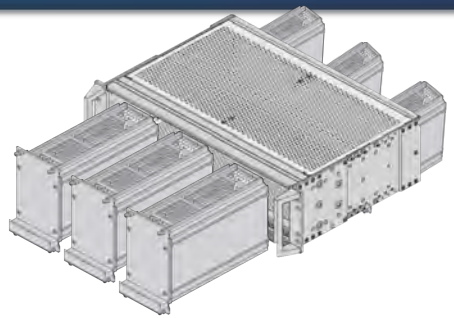
90 x 65 mm^2

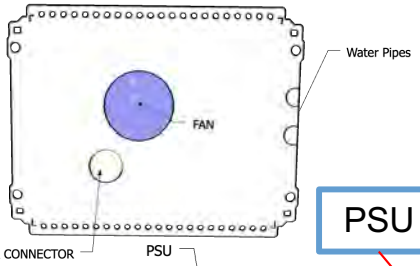
- 51% Area



Mechanical Layout

Design requirement:
- Keep present 3U 19'' crate





PSU

MDR Inputs

Signal Backplane

Power Backplane

DigiOpt12

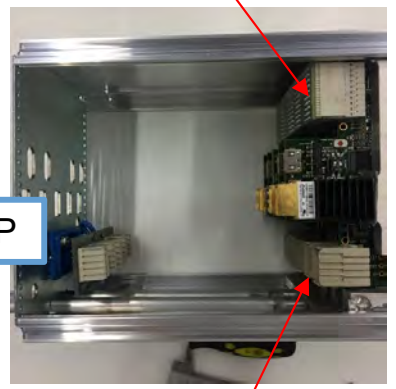
Signal Backplane

Ethernet Output
GTS Connection

PACE-CAP

STARE

Cooling plates



Power Backplane

Cooling

Heat
Exchanger

Side View

Top View

Wider for better pipe soldering
and/or commercial solutions

Work Status

Finished

- PSU and Power Backplane PCB
- Component procurement

On-going

- Signal Backplane
- PSU, Power Backplane PCB assembly

Started

- Mechanical structures
  - Top/Bottom cover plates
  - Side Panels: buy from Schroff
  - Rear panel/Front Panel cut-outs
- Cooling
  - DigiOpt12: cooling plates
  - CAP-STARE: need actual PCBs to define it (starting April)
  - Heat exchanger and pipe soldering and/or commercial solution

- **Milestone: one complete set for June tests**

Conclusions

On-going

- Conceived system achieves
  - Higher integration and compactness
  - Use of Ethernet readout
  - Easier maintenance (by using SOM modules)
  - Modularity
  - Backward compatibility
- Proof-of-concept test performed (July 2019, see N.K. talk in AGATA Week, 2019)

Works is progressing but need to keep track very closely to achieve milestones

Thank you for your attention